

Form PTQ-1449
(Rev. 2-88)U.S. DEPARTMENT OF COMMERCE
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6674-2APPLICATION NO.
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REYNICK

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GROUP

3829

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

EXAMINER'S INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
RK	5,963,492	10/05/99	Hsu	365	201	
RK	5,790,565	08/04/98	Sakaguchi	371	27.1	
RK	5,917,331	06/29/99	Persons	324	765	
RK	5,944,847	08/31/99	Sanada	714	741	
RK	5,939,897	08/17/99	Ayers, et al	326	58	
RK	5,519,333	05/21/96	Righter	324	765	
RK	5,939,894	08/17/99	Yamauchi, et al	324	765	

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FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

RK		Nguyen, S.V., "High-Density Plasma Chemical Vapor Deposition of Silicon-Based Dielectric Films for Integrated Circuits," IBM Journal of Research & Development, Vol. 43, No. 1/2 (1999). (Month Unavailable)

EXAMINER

DATE CONSIDERED

6-19-03

* EXAMINER: Initial if a citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.